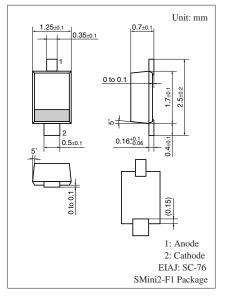
MA2J727

Silicon epitaxial planar type

For super high speed switching For small current rectification

Features

- $V_R = 50$ V is guaranteed
- $I_{F(AV)} = 200 \text{ mA}$ rectification is possible



Absolute Maximum Ratings $T_a = 25^{\circ}C$

| Parameter | Symbol | Rating | Unit |
|---|--------------------|-------------|------|
| Reverse voltage | V _R | 50 | V |
| Repetitive peak reverse voltage | V _{RRM} | 50 | V |
| Peak forward current | I_{FM} | 300 | mA |
| Forward current (Average) | I _{F(AV)} | 200 | mA |
| Non-repetitive peak forward surge current * | I _{FSM} | 1 | А |
| Junction temperature | Tj | 150 | °C |
| Storage temperature | T _{stg} | -55 to +150 | °C |

Marking Symbol: 2F

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|-------------------------|-----------------|--|-----|-----|------|------|
| Reverse current | I _R | $V_R = 50 V$ | | | 200 | μΑ |
| Forward voltage | V _{F1} | $I_F = 30 \text{ mA}$ | | | 0.36 | V |
| | V _{F2} | I _F = 200 mA | | | 0.55 | V |
| Terminal capacitance | Ct | $V_R = 0 V, f = 1 MHz$ | | 30 | | pF |
| Reverse recovery time * | t _{rr} | $I_F = I_R = 100 \text{ mA}$ | | 3.0 | | ns |
| | | $I_{rr} = 10 \text{ mA}, R_{L} = 100 \Omega$ | | | | |

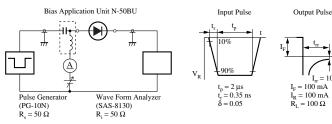
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

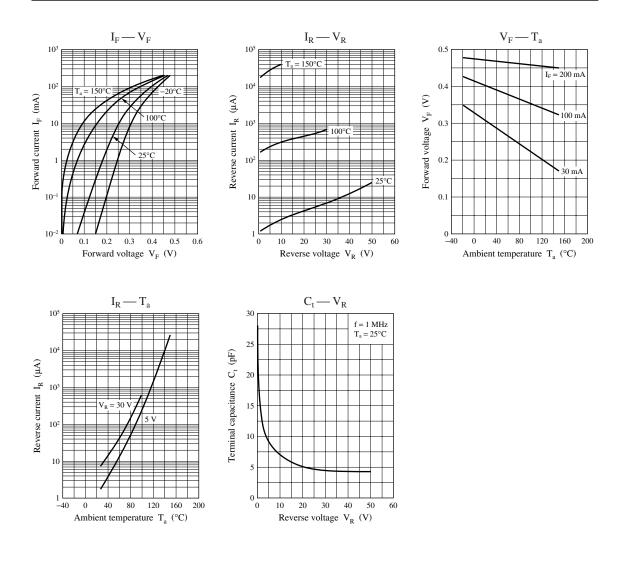
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

4. *: trr measurement circuit

 $= 10 \, \text{mA}$

3. Absolute frequency of input and output is 1 GHz.





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